NOVEMBER 1985-REVISED APRIL 1988

This Data Sheet is Applicable to All TMS27C64s and TMS27PC64s Symbolized with Code "A" as Described on Page 12.

- Organization . . . 8K × 8
- Single 5-V Power Supply
- Pin Compatible with Existing 64K MOS ROMs, PROMs, and EPROMs
- All Inputs/Outputs Fully TTL Compatible
- Max Access/Min Cycle Times

VCC ±5%	VCC ±10%	
'27C64-100		100 ns
'27C/PC64-120	'27C/PC64-12	120 ns
'27C/PC64-1	'27C/PC64-15	150 ns
'27C/PC64-2	'27C/PC64-20	200 ns
'27C/PC64	'27C/PC64-25	250 ns

- Power Saving CMOS Technology
- Very High-Speed SNAP! Pulse Programming or Fast Programming Algorithms
- 3-State Output Buffers
- 400 mV Guaranteed DC Noise Immunity with Standard TTL Loads
- Latchup Immunity of 250 mA on All Input and Output Lines
- Low Power Dissipation (VCC = 5.25 V)
 - Active . . . 158 mW Worst Case - Standby . . . 1.4 mW Worst Case (CMOS Input Levels)
- PEP4 Version Available with 168 Hour Burn-In, and also Extended Guaranteed **Operating Temperature Ranges**

((TOP VIEW)								
V _{PP}	ſτ	²⁸ □ ∨ _{CC}							
A12[]2	27 PGM							
A7 🗀]3	26 □ NC							
A6 🗌]4	25 🗆 A8							
A5 [5	24 🗆 A9							
A4 🗀	6	23 🗆 A11							
A3 🗀	7	22 <u>□ G</u>							
A2 🗀	8	21 A10							
A1 🗀	9	20 🗖 Ē							
A0 [10	19 🗖 Q8							
Q1 [11	18 🗖 0.7							
02	12	17 🗖 🛛 🖸 6							
03 [13	16 □ 0.5							
GND 🗀	14	15 Q4							

J & N PACKAGE

	PIN NOMENCLATURE								
A0-A12	Address Inputs								
Ē	Chip Enable Power Down								
ढ	Output Enable								
GND	Ground								
NC	No Connection								
NU	Make No External Connection								
PGM	Program								
Q1-Q8	Outputs								
Vcc	5-V Power Supply								
VPP	12-13 V Programming Power Supply								

description

The TMS27C64 series are 65,536-bit, ultraviolet-light erasable, electrically programmable read-only memories.

The TMS27PC64 series are 65.536-bit, one-time, electrically programmable read-only memories.

These devices are fabricated using power saving CMOS technology for high-speed and simple interface with MOS and bipolar circuits. All inputs (including program data inputs) can be driven by Series 74 TTL circuits without the use of external pull-up resistors. Each output can drive one Series 74 TTL circuit without external resistors.

The data outputs are three-state for connecting multiple devices to a common bus. The TMS27C64 and the TMS27PC64 are pin compatible with 28-pin 64K MOS ROMs, PROMs, and EPROMs.

The TMS27C64 EPROM is offered in a dual-in-line ceramic package (J suffix) designed for insertion in mounting hole rows on 15,2-mm (600-mil) centers. The TMS27C64 is available with two guaranteed temperature ranges of 0°C to 70°C and -40°C to 85°C (TMS27C64-__JL and TMS27C64-__JE, respectively). The TMS27C64 is also offered with 168-hour burn-in on both temperature ranges (TMS27C64-__JL4 and TMS27C64-__JE4, respectively). (See table below).

The TMS27PC64 PROM is offered in a dual-in-line plastic package (N suffix) designed for insertion in mounting hole rows on 15,2-mm (600-mil) centers. The TMS27PC64 is guaranteed for operation from 0°C to 70°C.

All package styles conform to JEDEC standards.

EPROM	WITHOUT		SUFFIX FOR PEP4 168 HR. BURN-IN VS TEMPERATURE RANGES			
1	0°C to 70°C	-40°C to 85°C	0°C to 70°C	-40°C to 85°C		
TMS27C64-XXX	JL	JE	JL4	JE4		

These EPROMs and PROMs operate from a single 5-V supply (in the read mode), thus are ideal for use in microprocessor-based systems. One other 12-13 V supply is needed for programming. All programming signals are TTL level. These devices are programmable by either Fast or SNAPI Pulse programming algorithms. Fast programming uses a Vpp of 12.5 V and a VCC of 6.0 V for a nominal programming time of two minutes. SNAPI Pulse programming uses a Vpp of 13.0 V and a VCC of 6.5 V for a nominal programming time of one second. For programming outside the system, existing EPROM programmers can be used. Locations may be programmed singly, in blocks, or at random.

operation

There are seven modes of operation listed in the following table. Read mode requires a single 5-V supply. All inputs are TTL level except for Vpp during programming (12.5 V for Fast, or 13.0 V for SNAPI Pulse) and 12 V on A9 for signature mode.



				MODE				
FUNCTION	Read	Output Disable	Standby	Programming	Verify	Program Inhibit	_	ature ode
E	VIL	VIL	V _{IH}	VIL	VIL	VIH	V	IL
ত্ত	VIL	VIH	χ [†]	VIH	VIL	х	V	iL,
PGM	VIH	VIH	×	VIL	VIH	х	v	HH.
VPP	Vcc	Vcc	Vcc	Vpp	VPP	Vpp	V	СС
Vcc	Vcc	Vcc	Vcc	vcc	Vcc	vcc	V	cc
A9	, x	×	×	х	x	×	VH‡	VH‡
AO	х	х	х	×	×	×	VIL	VIH
		<u> </u>					CC	DE
Q1-Q8	DOUT	HI-Z	HI-Z	DIN	DOUT	HI-Z	MFG	DEVICE
				1 1		1 '	97	07

 $^{^{\}dagger}$ X Can be V_{IL} or V_{IH}. ‡ V_H = 12 V ± 0.5 V.

read/output disable

When the outputs of two or more TMS27C64s or TMS27PC64s are connected in parallel on the same bus, the output of any particular device in the circuit can be read with no interference from the competing outputs of the other devices. To read the output of a single device, a low-level signal is applied to the \overline{E} and \overline{G} pins. All other devices in the circuit should have their outputs disabled by applying a high-level signal to one of these pins. Output data is accessed at pins Q1 through Q8.

latchup immunity

Latchup immunity on the TMS27C64 and TMS27PC64 is a minimum of 250 mA on all inputs and outputs. This feature provides latchup immunity beyond any potential transients at the P.C. board level when the devices are interfaced to industry-standard TTL or MOS logic devices. Input/output layout approach controls latchup without compromising performance or packing density.

For more information see application report SMLA001; "Design Considerations; Latchup Immunity of the HVCMOS EPROM Family," available through TI Field Sales Offices.

power down

Active I_{CC} current can be reduced from 30 mA to 500 μ A (TTL-level inputs) or 250 μ A (CMOS-level inputs) by applying a high TTL signal to the \overline{E} pin. In this mode all outputs are in the high-impedance state.

erasure (TMS27C64)

Before programming, the TMS27C64 EPROM is erased by exposing the chip through the transparent lid to high intensity ultraviolet light (wavelength 2537 angstroms). EPROM erasure before programming is necessary to assure that all bits are in the logic 1 (high) state. Logic Os are programmed into the desired locations. A programmed logic 0 can be erased only by ultraviolet light. The recommended minimum ultraviolet light exposure dose (UV intensity × exposure time) is 15 watt-seconds per square centimeter.

A typical 12-milliwatt-per-square-centimeter, filterless UV lamp will erase the device in 21 minutes. The lamp should be located about 2.5 centimeters above the chip during erasure. It should be noted that normal ambient light contains the correct wavelength for erasure. Therefore, when using the TMS27C64, the window should be covered with an opaque label.

initializing (TMS27PC64)

The one-time programmable TMS27PC64 PROM is provided with all bits in the logic 1 state, then logic 0s are programmed into the desired locations. Logic 0s programmed into a PROM cannot be erased.

SNAP! Pulse programming

The 64K EPROM and PROM can be programmed using the TI SNAP! Pulse programming algorithm illustrated by the flowchart of Figure 1, which can reduce programming time to a nominal of one second. Actual programming time will vary as a function of the programmer used.

Data is presented in parallel (eight bits) on pins Q1 through Q8. Once addresses and data are stable, PGM is pulsed.

The SNAP! Pulse programming algorithm uses initial pulses of 100 microseconds (μ s) followed by a byte verification to determine when the addressed byte has been successfully programmed. Up to 10 (ten) 100 μ s pulses per byte are provided before a failure is recognized.

The programming mode is achieved when Vpp = 13.0 V, $V_{CC} = 6.5 \text{ V}$, $\overline{G} = V_{IH}$, and $\overline{E} = V_{IL}$. More than one device can be programmed when the devices are connected in parallel. Locations can be programmed in any order. When the SNAP! Pulse programming routine is complete, all bits are verified with $V_{CC} = V_{PP} = 5 \text{ V}$.

Fast programming

The 64K EPROM and PROM can be programmed using the Fast programming algorithm illustrated by the flowchart in Figure 2. During Fast programming, data is presented in parallel (eight bits) on pins Q1 through Q8. Once addresses and data are stable, \overline{PGM} is pulsed. The programming mode is achieved when VPP = 12.5 V, VCC = 6.0 V, \overline{G} = V_{IH}, and \overline{E} = V_{IL}. More than one device can be programmed when the devices are connected in parallel. Locations can be programmed in any order.

Fast programming uses two types of programming pulses: Prime and Final. The length of the Prime pulse is 1 millisecond; this pulse is applied X times. After each Prime pulse, the byte being programmed is verified. If the correct data is read, the Final programming pulse is applied; if correct data is not read, an additional 1 millisecond pulse is applied up to a maximum X of 25. The Final programming pulse is 3X long. This sequence of programming and verification is performed at $V_{CC} = 6.0 \text{ V}$ and $V_{CC} = 12.5 \text{ V}$. When the full Fast programming routine is complete, all bits are verified with $V_{CC} = V_{CC} = 5.0 \text{ V}$.

program inhibit

Programming may be inhibited by maintaining a high level input on the \overline{E} or \overline{PGM} pin.

program verify

Programmed bits may be verified with Vpp = 12.5 V when $\overline{G} = V_{|L}$, $\overline{E} = V_{|L}$, and $\overline{PGM} = V_{|H}$.

signature mode

The signature mode provides access to a binary code identifying the manufacturer and type. This mode is activated when A9 is forced to 12 V \pm 0.5 V. Two identifier bytes are accessed by A0; i.e., A0 = V_{IL} accesses the manufacturer code, which is output on Q1-Q8; A0 = V_{IH} accesses the device code, which is output on Q1-Q8. All other addresses must be held at V_{IL}. Each byte possesses odd parity on bit Q8. The manufacturer code for these devices is 97, and the device code is 07.



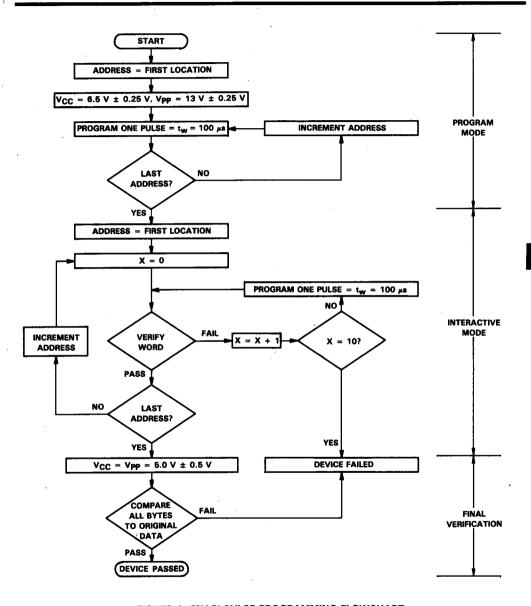


FIGURE 1. SNAP! PULSE PROGRAMMING FLOWCHART

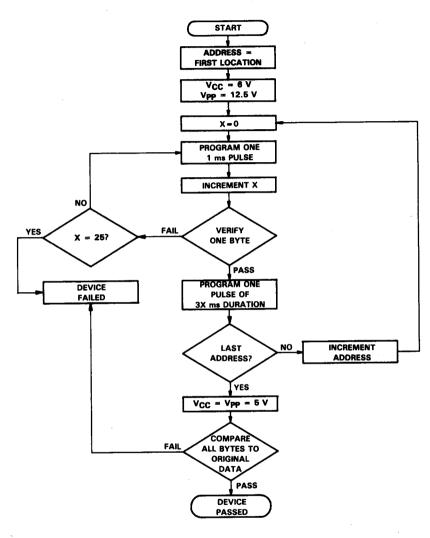
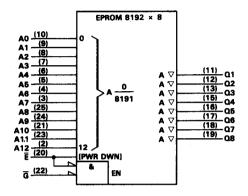
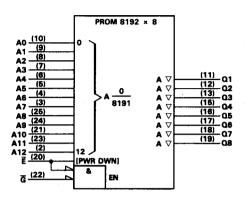


FIGURE 2. FAST PROGRAMMING FLOWCHART

logic symbols†





[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. J and N packages illustrated.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, VCC (see Note 1)	0.6 V to 7 V
Supply voltage range, Vpp (see Note 1)	
Input voltage range (see Note 1): All inputs except A90	.6 V to 6.5 V
A90.6	i V to 13.5 V
Output voltage range (see Note 1)0.6 V to	o VCC + 1 V
Operating free-air temperature range ('27C64JL and JL4; '27PC64NL)	0°C to 70°C
Operating free-air temperature range ('27C64JE and JE4) 4	O°C to 85°C
Storage temperature range65	°C to 150°C

^{*}Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "Recommended Operating Onditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: Under absolute maximum ratings, voltage values are with respect to GND.

recommended operating conditions

				'27C84-100 '27C/PC64-120 '27C/PC64-1 '27C/PC64-2 '27C/PC64			'27C	/PC64-1 /PC64-1 /PC64-2 /PC64-2	5 0	UNIT
				MIN	NOM	MAX	MIN	NOM	MAX	
		Read mode (see !	Note 2)	4.75	5	5.25	4.5	5	5.5	
Voo	V _{CC} Supply voltage	Supply voltage Fast programming algorithm		5.75	6	6.25	5.75	6	6.25	V
ACC Oubbit torrage	SNAP! Pulse programming algorithm		6.25	6.50	6.75	6.25	6.5	6.75	٧	
	Read mode (see Note 3)			V _{CC} -0.6		V _{CC} +0.6	V _{CC} -0.6	,v	CC+0.6	V
Vpp	Supply voltage	Fast programming		12	12.5	13	12	12.5	13	V
VPP.	Supply voltage		ramming algorithm	12.75	13	13.25	12.75	13	13.25	V
			TTL	2		V _{CC} +1	2		V _{CC} +1	V
VIΗ	High-level input	voltage	CMOS	V _{CC} -0.2		V _{CC} +1	V _{CC} -0.2		V _{CC} +1	V
		TTL	-0.5		0.8	-0.5		0.8	٧	
٧ _{IL}	V _{II} I ow-level input voltage L		CMOS	-0.5		0.2	-0.5		0.2	V
TA	Operating free-a	ir temperature (se	e table, page 2)	(see	table, pa	ige 2)	(see ta	ble, pag	e 2)	°C

NOTES: 2. V_{CC} must be applied before or at the same time as Vpp and removed after or at the same time as Vpp. The device must not be inserted into or removed from the board when Vpp or V_{CC} is applied.

3. Vpp can be connected to VCC directly (except in the program mode). VCC supply current in this case would be ICC + Ipp.

electrical characteristics over full ranges of recommended operating conditions

PARAMETER			PARAMETER TEST CONDITIONS					
		I _{OH} = -2.5 mA					V	
۷он	High-level output voltage		I _{OH} = -20 μA	V _{CC} -0	.1 .		V	
			I _{OL} = 2.1 mA			0.4	V	
VOL			I _{OL} = 20 μA			0.1	٧	
l _l	Input current (leakage)		V _I = 0 V to 5.5 V			±1	μΑ	
lo	Output current (leakage) Vpp supply current		V _O = 0 V to V _{CC}			± 1	μΑ	
IPP1			Vpp = Vcc = 5.5 V		1_	10	μΑ	
IPP2	Vpp supply current (duri	na program pulse)	V _{PP} = 13 V		35	50	mA	
112	VCC supply current	TTL-input level	V _{CC} = 5.5 V, E = V _{IH}		250	500	μΑ	
ICC1	(standby)	CMOS-input level	V _{CC} = 5.5 V, E = V _{CC}		100	250	μΑ	
ICC2	VCC supply current (act	ive)	$V_{CC} = 5.5 \text{ V}, \overline{E} = V_{IL},$ $t_{cycle} = \text{minimum cycle time},$ outputs open		15	30	mA	

 $^{^{\}dagger}$ Typical values are at $T_{A} = 25\,^{\circ}$ C and nominal voltages.

capacitance over recommended supply voltage range and operating free-air temperature range, $f=1~\text{MHz}^{\ddagger}$

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Ci	Input capacitance	V _I = 0 V, f = 1 MHz		6	10	pF
Co	Output capacitance	V _O = 0 V, f = 1 MHz		10	14	pF

 $^{^{\}dagger}$ Typical values are at T_A = 25 °C and nominal voltages.

[‡]Capacitance measurements are made on sample basis only.



switching characteristics over full ranges of recommended operating conditions (see Notes 4 and 5)

PARAMETER		TEST CONDITIONS (SEE NOTES 4 AND 5)	27C64-100		^{27C64-100}		′27C64-100		′27C64-100		′27C84-100		'27C/PC		'27C/P	C64-1 C64-15	UNIT
	_	(SEE NOTES 4 AND 5)	MIN	MAX	MIN	MAX	MIN	MAX									
ta(A)	Access time from address			100		120		150	ns								
t _{a(E)}	Access time from chip enable	C _L = 100 pF,		100		120		150	ns								
t _{en(G)}	Output enable time from G			50		55		75	ns								
^t dis	Output disable time from G or E, whichever occurs first	1 Series 74 TTL Load, Input t _r ≤20 ns,	0	40	٥	45	0	60	ns								
^t v(A)	Output data valid time after change of address, \overline{E} , or \overline{G} , whichever occurs first †	Input t _f ≤20 ns	0		o		0		ns								

PARAMETER		TEST CONDITIONS		'27C/PC64-2 '27C/PC64-20		'27C/PC64 '27C/PC64-25	
		(SEE NOTES 4 AND 5)	MIN	MAX	MIN	MAX	
ta(A)	Access time from address			200		250	ns
ta(E)	Access time from chip enable			200		250	ns
ten(G)	Output enable time from G	$C_L = 100 pF$,		75		100	ns
t _{dis}	Output disable time from $\overline{\mathbb{G}}$ or $\overline{\mathbb{E}}$, whichever occurs first †	1 Series 74 TTL Load, Input t _r ≤ 20 ns,	0	60	О	60	ns
t _V (A)	Output data valid time after change of address, E, or G, whichever occurs first	input t _f ≤20 ns	0		0		ns

[†]Value calculated from 0.5 V delta to measured level. This parameter is only sampled and not 100% tested.

switching characteristics for programming: $V_{CC}=6$ V and $V_{PP}=12.5$ V (Fast) or $V_{CC}=6.50$ V and $V_{PP}=13.0$ V (SNAP! Pulse), $T_{A}=25$ °C (see Note 4)

	PARAMETER			UNIT
^t dis(G)	Output disable time from G	0	130	ns
ten(G)	Output enable time from G		150	ns

- NOTES: 4. For all switching characteristics the input pulse levels are 0.40 V to 2.4 V. Timing measurements are made at 2.0 V for logic 1 and 0.8 V for logic 0. (Reference page 10.)
 - 5. Common test conditions apply for tdis except during programming.

6

TMS27C64 65,536-BIT UV ERASABLE PROGRAMMABLE READ-ONLY MEMORY TMS27PC64 65,536-BIT PROGRAMMABLE READ-ONLY MEMORY

recommended timing requirements for programming: $V_{CC}=6\ V$ and $\overline{V_{PP}}=12.5\ V$ (Fast) or $V_{CC}=6.5\ V$ and $\overline{V_{PP}}=13.0\ V$ (SNAP! Pulse), $\overline{V_{PP}}=25\ C$ (see Note 4)

			MIN	NOM	MAX	UNIT
tw(IPGM)	Initial program pulse duration	Fast programming algorithm	0.95	1	1.05	ms
		SNAP! Pulse programming algorithm	95	100	105	μ8
tw(FPGM)	Final pulse duration	Fast programming only	2.85		78.75	ms
t _{su(A)}	Address setup time		2			μ8
t _{su(E)}	E setup time		2			μ8
t _{su(G)}	G setup time		2			μ8
t _{su(D)}	Data setup time		2			μ8
t _{su(VPP)}	Vpp setup time		2			μ8
t _{su(VCC)}	V _{CC} setup time		2			#8
th(A)	Address hold time					μ8
th(D)	Data hold time		2			μS

NOTE 4: For all switching characteristics the input pulse levels are 0.40 V to 2.4 V. Timing measurements are made at 2.0 V for logic 1 and 0.8 V for logic 0 (reference below).

PARAMETER MEASUREMENT INFORMATION

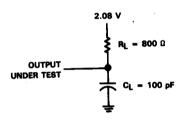
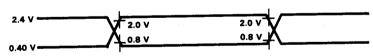
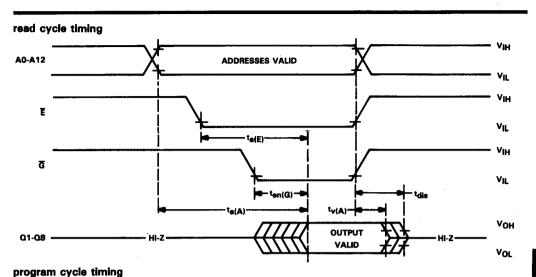


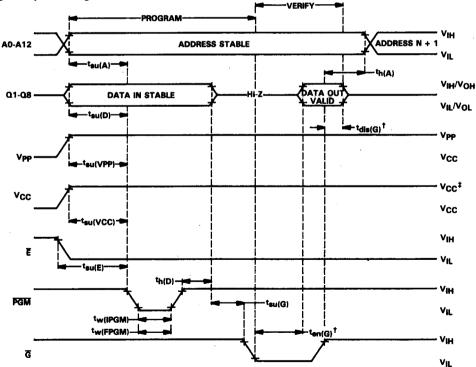
FIGURE 3. OUTPUT LOAD CIRCUIT

AC testing input/output wave forms



A.C. testing inputs are driven at 2.4 V for logic 1 and 0.4 V for logic 0. Timing measurements are made at 2.0 V for logic 1 and 0.8 V for logic 0 for both outputs.





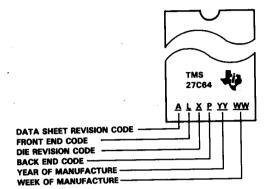
†t_{dis(G)} and t_{en(G)} are characteristics of the device but must be accommodated by the programmer.

^{\$12.5} V Vpp and 6.0 V Vcc for Fast programming; 13.0 V Vpp and 6.5 V Vcc for SNAPI Pulse programming.



device symbolization

This data sheet is applicable to all TI TMS27C64 CMOS EPROMs and TMS27PC64 PROMs with the data sheet revision code "A" as shown below.



R

TYPICAL TMS27C/PC64 CHARACTERISTICS

